



Material Content Data Sheet



Sales Product Name	TLE4241GM			Issued	20. July 2018			
MA#	MA000982346							
Package	PG-DSO-8-16			Weight*	83.23 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.036	2.45	2.45	24457	24457
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8617	
wire	non noble metal	copper	7440-50-8	29.121	34.99	35.90	349884	359040
	noble metal	gold	7440-57-5	0.161	0.19	0.19	1939	1939
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165
encapsulation	plastics	epoxy resin	-	4.460	5.36		53587	
	inorganic material	silicondioxide	60676-86-0	43.923	52.77	58.25	527720	582472
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9778	9778
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7813	7813
glue	plastics	acrylic resin	-	0.266	0.32		3190	
	noble metal	silver	7440-22-4	0.941	1.13	1.45	11311	14501
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com